

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number: [5013310207](#)
Status: **Active**
Overview: [picoclap](#)
Description: 1.00mm (.039") Pitch Pico-Clasp™ Wire-to-Board Header, Surface Mount, Single Row, Vertical, with Friction Lock, 2 Circuits, with Cover Tape, Lead-free

Documents:

[3D Model](#) [Product Specification PS-501331-001 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

General

Product Family	PCB Headers
Series	501331
Application	Wire-to-Board
Overview	picoclap
Product Name	Pico-Clasp™

Physical

Breakaway	No
Circuits (Loaded)	2
Color - Resin	Natural
Durability (mating cycles max)	30
Glow-Wire Compliant	No
Lock to Mating Part	Yes
Material - Metal	Phosphor Bronze
Material - Plating Mating	Tin
Material - Plating Termination	Tin
Material - Resin	Nylon
Number of Rows	1
Orientation	Vertical
PCB Locator	No
PCB Retention	Yes
Packaging Type	Embossed Tape on Reel
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Polarized to Mating Part	Yes
Polarized to PCB	No
Robotic Placement	Vacuum Pick-Up Tape
Stackable	No
Temperature Range - Operating	-40°C to +85°C
Termination Interface: Style	Surface Mount

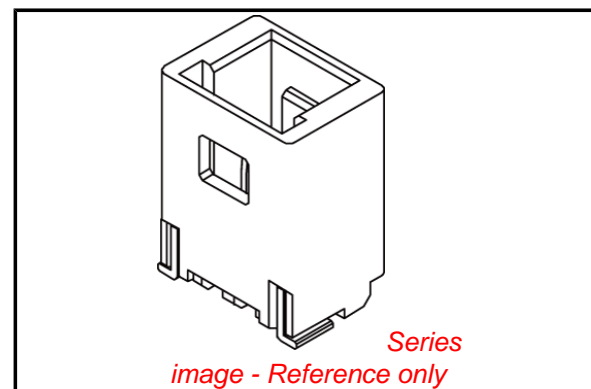
Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	50V AC (RMS)/DC

Material Info

Reference - Drawing Numbers

Packaging Specification	SPK-501331-001
Product Specification	PS-501331-001, RPS-501331-001, RPS-501331-002, RPS-501331-003, RPS-501331-006, RPS-501331-007
Sales Drawing	SD-501331-001, SD-501331-003



EU RoHS

**ELV and RoHS
Compliant**
REACH SVHC
 Not Reviewed
**Halogen-Free
Status**

China RoHS



Not Reviewed

**Need more information on product
environmental compliance?**

Email productcompliance@molex.com
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[501331Series](#)

Mates With

[501330](#) Pico-Clasp™ Wire-to-Board Female Housing

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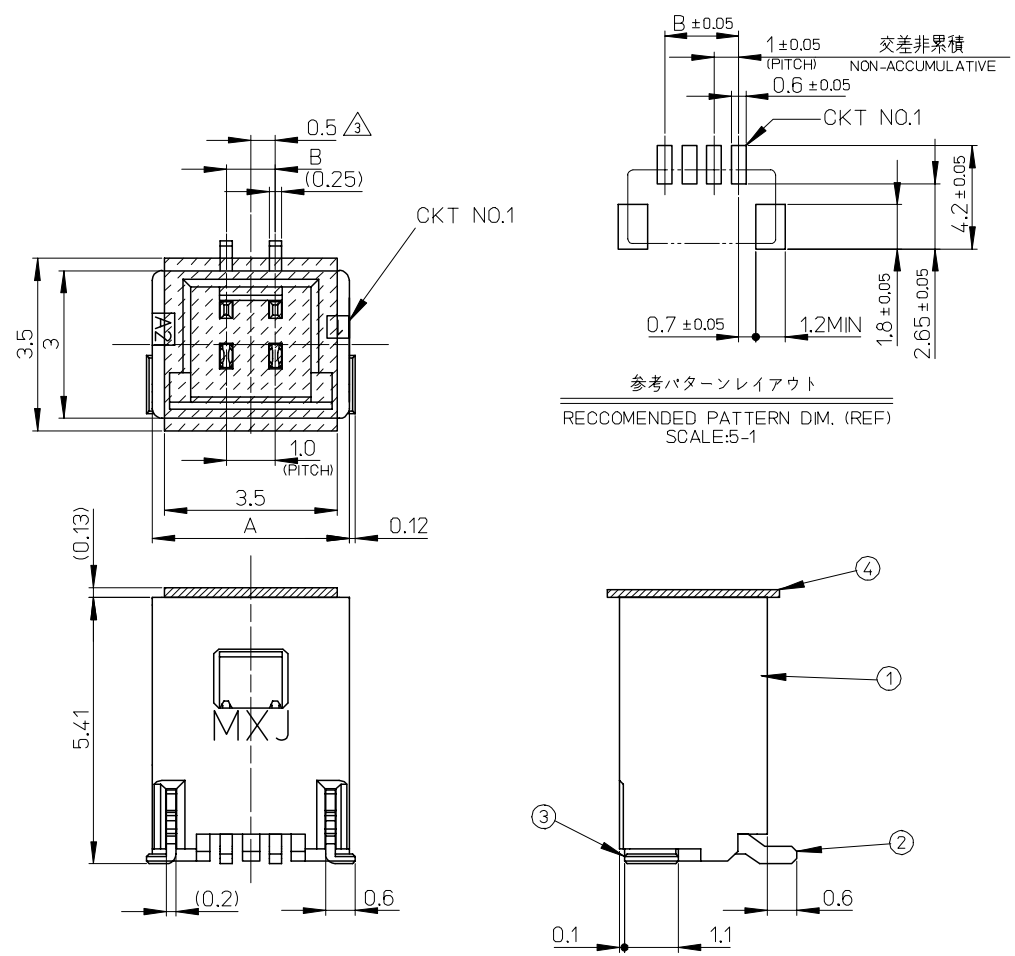
番号 NO.	部品 PART	材質 MATERIAL
①	ウェハー WAFER	46ナイロン UL94V-0 色:自然色 46 NYLON , UL94V-0 , COLOR:NATURAL
②	ソルダーピン SOLDER PIN	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
③	ネイル NAIL	りん青銅 PHOSPHOR BRONZE 錫メッキ: 1.0μmMIN. TIN ニッケルメッキ(下地): 1.0μmMIN. NICKEL(UNDER PLATING)
④	カバーテープ COVER TAPE	ポリイミドテープ POLYIMIDE TAPE

NOTES.

1. 嵌合相手: 501330-****
MATE WITH: 501330-****
2. ソルダーピン及びネイル平坦度は、0.1MAX.
SOLDER PIN AND NAIL COPLANARITY TO BE 0.1MAX.
- △ 極数=偶数に適用
APPLY FOR CKT SIZE=EVEN
4. 6~15極については、SD-501331-002を参照下さい。
REFER TO SD-501331-002 ABOUT 6-15CKT.
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.

※対応可能な極数は、別途お問い合わせ下さい。

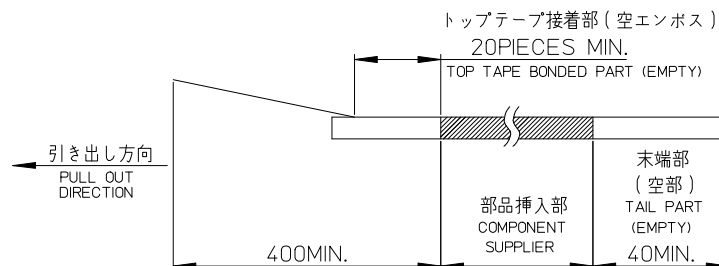
4.0	7.0	501331-0509	5	501331-**09
3.0	6.0	501331-0409	4	
2.0	5.0	501331-0309	3	
1.0	4.0	501331-0209	2	
B	A	MATERIAL NO.	CKT.	MODEL NO.



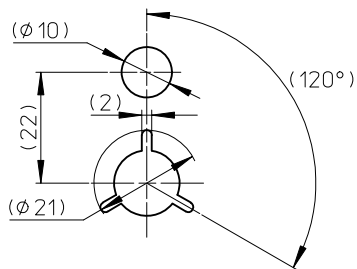
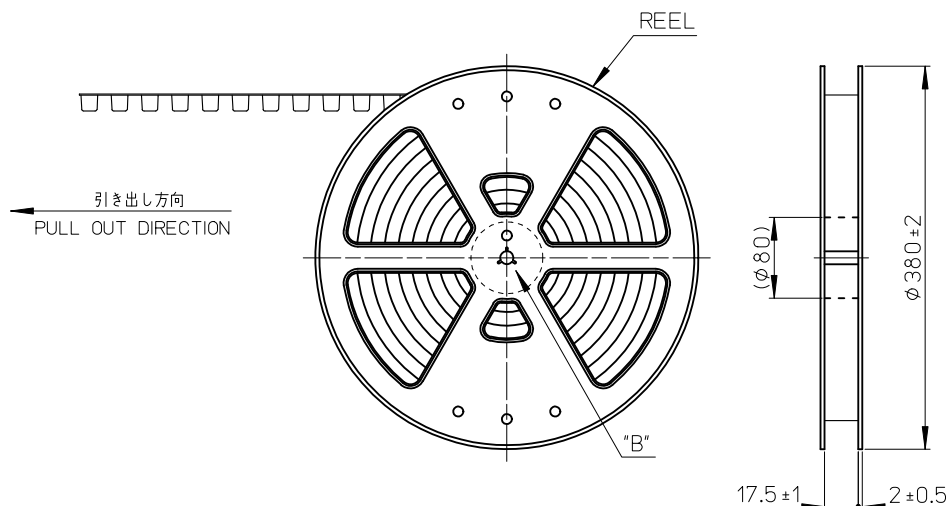
REVISED EC NO: J2007-2540 DRWN: A0YAGI CHKD: YMAEDA APPR: NUKITA	DESCRIPTION 2007/03/13 2007/03/13 2007/03/16	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
		10 UNDER	± 0.2	DRAWN BY NYOSHIDA	DATE 2004/07/30	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) 2-5CKT		MOLEX INCORPORATED		SHEET NO. 1 OF 1
10 OVER 30 UNDER	± 0.25	CHECKED BY MYAGI	DATE 2004/07/30	APPROVED BY MIYAZAWA		DATE 2004/07/30	DOCUMENT NO. SD-501331-001		MATERIAL NO.	
30 OVER	± 0.3	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

NOTES

1. 製品詳細寸法は製品単体図面を参照して下さい。
FOR DETAIL OF CONNECTOR DIMENSIONS, PLEASE SEE THE DRAWING OF CONNECTOR ITSELF (NOT PACKAGED).
2. 梱包数量: 1100個/リール
NUMBER OF CONNECTORS: 1100PIECES/REEL
3. リードテープ長さ
LEAD TAPE LENGTH

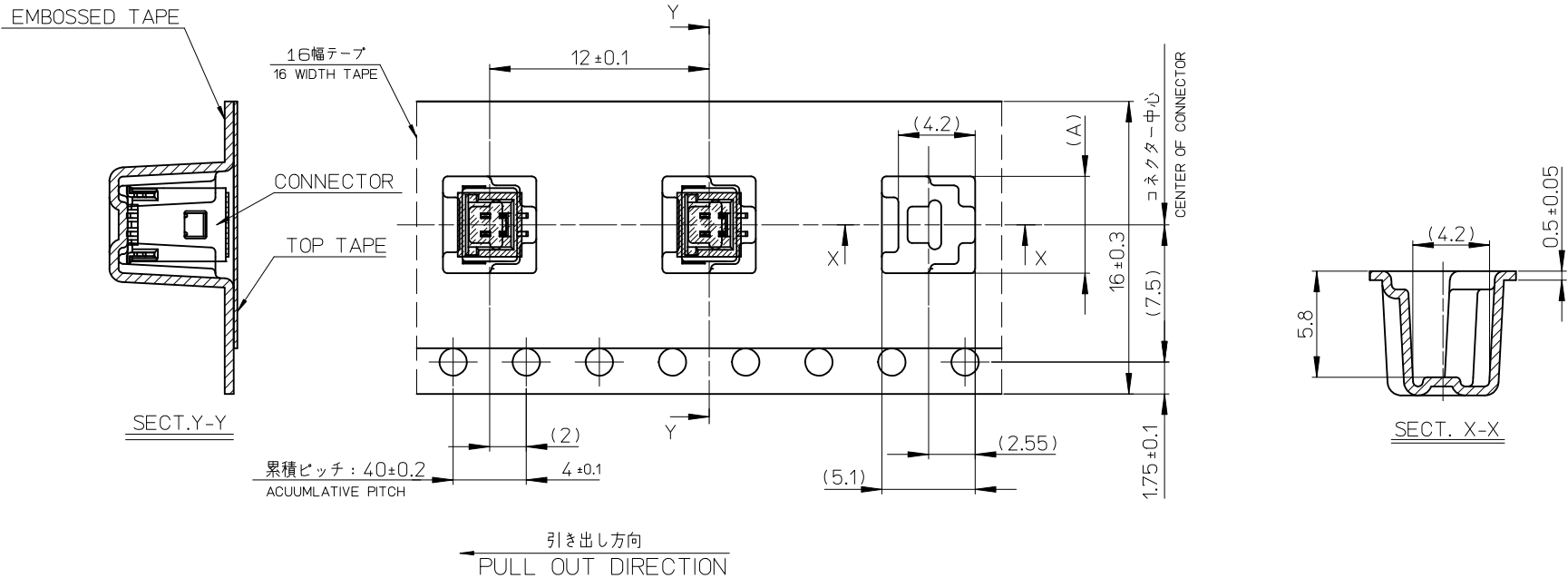


4. 材料
MATERIAL
キャリアテープ: ポリプロピレン
CARRIER TAPE: POLYPROPYLENE
トップテープ: PET、PE、REF
TOP TAPE
リール: ポリスチレン<リサイクル材を含む>
REEL: POLYSTYRENE <RECYCLE MATERIAL CONTAINED>
5. ELV及びRoHS適合品。
ELV AND RoHS COMPLIANT.
6. 本製品は乾燥剤入り、ハイバリア梱包仕様である。
(501331-0607~1507以外)
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.
(BESIDES 501331-0607~1507)



DETAIL "B"

REVISED EC NO: J2010-0951 2009/12/16 DRWN: NITO CHKD: KASAKAWA 2010/01/05 APPR: NUKITA 2010/01/06	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG			
		10 OVER 30 UNDER	±0.25	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE SHEET 2			
ANGULAR ±1 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		DOCUMENT NO. SD-501331-003		SHEET NO. 1 OF 2		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION	



8.3	501331-0509	501331-0507	5	501331-***7
7.3	501331-0409	501331-0407	4	
6.3	501331-0309	501331-0307	3	
5.3	501331-0209	501331-0207	2	
(A)	CONNECTOR	MATERIAL NO.	CKT.	MODEL NO.

REVISED EC NO: J2010-0951 2009/12/16 DRWN: NITO 2010/01/05 CHKD: KASAKAWA 2010/01/06 APPR: NUKITA	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE MM ONLY	SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER ± 0.2 10 OVER 30 UNDER ± 0.25 30 OVER ± 0.3	DRAWN BY NYOSHIDA	DATE 2005/01/18	TITLE 1.0 WIRE TO BOARD CONN. WAFER ASS'Y (1-ROW S/T) EMBSTP PKG	
		ANGULAR ± 1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	CHECKED BY MYAGI	DATE 2005/01/18	MOLEX INCORPORATED	
		SIZE A3	APPROVED BY ANODA	DATE 2005/01/18	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-501331-003